In accordance with an aspect of the present invention, a camera or optical module for a camera is provided, the camera or optical module comprising:

- a first substrate with a first optical device or plurality of optical devices,
- a second substrate with a second optical device or plurality of optical devices,
- and a spacer between the first substrate and the second substrate, the spacer having a first and a second attachment surface, the first substrate attached to the first attachment surface and the second spacer attached to the second attachment surface,
- the spacer having a through hole from the first attachment surface to the second attachment surface so that there is an interior space between the first substrate and the second substrate, the interior space being, for example hermetically, closed off,
- the first optical device(s) and the second optical device(s) being mutually arranged so that light impinging, from an object side, on the first optical device(s) is directed to the second optical device(s),
- the camera further comprising a screen device in the interior space, the screen device not being a coating layer on the first and/or second substrate or on the spacer, and the screen device blocking off stray light portions.

The screen device may for example comprise a screening wall or a plurality of screening walls that cover lateral walls of the interior space (the walls being formed by the spacer) and/or – if a plurality of first and second optical devices is present – that extend through the interior space to separate first-optical-device – second-optical-device pairs from each other. The walls may be thin of an essentially homogeneous thickness and/or they may be formed by a body that has at least one vertically extending through hole.

- a second substrate with a plurality of second optical devices, for example arranged in an array,

- and a spacer between the first substrate and the second substrate, the spacer having a first and a second attachment surface, the first substrate attached to the first attachment surface and the second spacer attached to the second attachment surface,

- the spacer having a through hole from the first attachment surface to the second attachment surface so that there is an interior space between the first substrate and the second substrate, the interior space being, for example hermetically, closed off,

- the first optical devices and the second optical devices being mutually arranged so that light impinging, from an object side, on a first optical device is directed to an assigned second optical device through the interior space,

- the camera further comprising a screen in the interior space, the screen device not being a coating layer on the first and/or second substrate or on the spacer, and the screen blocking off light portions from a first device from getting to a second device other than the assigned second device.

In embodiments of the second aspect of the invention, the screen may be formed by a screen device in accordance with the first aspect of the invention.

Alternatively, the screen may for example be formed by vertically protruding features of the first or second substrate or by features of the spacer and arranged to project into the through hole.

Screening wall(s) of the screen (i.e. for example of the screening device) may range from an image-side surface of the first substrate to an object-side surface of the

providing a first substrate wafer, a second substrate wafer and a spacer wafer with a plurality of through holes, of bringing, in arbitrary sequence the spacer wafer in contact with one of the first and of the second substrate wafer with a first portion of an adhesive in-between and introducing a screen device in at least one of the through holes, of thereafter bringing the second one of first and of the second substrate wafer and the spacer wafer in contact with each other with a second portion of an adhesive in-between, of hardening the second portion of the adhesive, and of dividing the resulting assembly into a plurality of camera-scale devices or modules, each having an interior space formed by one of said through holes. The screen device is not a coating layer on the first and/or second substrate or on the spacer.

The first portion of adhesive may be cured simultaneously with the second portion (for example in accordance with the teaching of PCT/CH 2009/000271 incorporated herein by reference) or may be cured prior to bringing the second one of the wafers in contact with the spacer wafer.

The step(s) of curing a portion/portions of the adhesive may comprise UV curing, i.e. curing by illuminating by ultraviolet radiation. Often, the first substrate wafer and/or the second substrate wafer has an Infrared (IR) filter that is needed for the camera. The transparency of IR filters for UV radiation is often limited, so that the curing may only take place from the side of the respective other substrate. However, if the other substrate is an optoelectronic substrate, it will not be transparent. This problem can be solved:

- Either by using an adhesive that is cured thermally, and/or that cures, at room temperature, slowly instead of by curing by UV irradiation,